

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior version, and listings, of claims in the application:

### *Listing of Claims:*

1. (Currently Amended) A printed circuit board comprising:

a printed wiring board;

a at least one component mounted ~~on said~~ on the printed wiring board, wherein the printed circuit board has a ~~cavity~~ volume of space with one or more openings ~~to the~~ on the surface of the printed circuit board; and

an electrically non-conductive filler material disposed in the ~~cavity~~ space and on the surface of the printed circuit board ~~immediately surrounding the cavity~~ so as to bridge across the one or more openings of the ~~cavity~~ space and at least partially infill the ~~cavity~~ space, wherein the filler material renders the ~~cavity~~ space substantially inaccessible to subsequently-applied coatings.

2. (Canceled)

3. (Currently Amended) The printed circuit board of claim 1, wherein the ~~cavity~~ comprises a volume of space defined is bounded by leads of said component, ~~said component body~~ a body of said component, and said printed wiring board, wherein the ~~volume of space has a plurality of~~ at least one of the one or more openings ~~to the~~ on the surface of the printed circuit board are located between neighboring component leads.

4. (Currently Amended) The printed circuit board of claim 1, wherein the at least one component comprises a plurality of components, and wherein the ~~cavity~~ comprises a volume of space between is bounded by neighboring two or more of the plurality of components ~~mounted on the printed wiring board~~.

5. (Currently Amended) The printed circuit board of claim 1, wherein the ~~eavity~~  
~~comprises a volume of space~~ is bounded by ~~between a component~~ the component ~~mounted~~  
~~on the printed wiring board~~ and the printed wiring board.

6. (Original) The printed circuit board of claim 1, wherein said filler material is  
thixotropic.

7. (Original) The printed circuit board of claim 1, wherein said filler material is an epoxy.

8. (Previously Presented) The printed circuit board of claim 7, wherein said epoxy is one of  
the family of Bisphenol-A epoxies mixed with an amine hardner.

9. (Original) The printed circuit board of claim 7, wherein said epoxy is a thermally cured  
epoxy.

10. (Original) The printed circuit board of claim 7, wherein said epoxy is a latex based  
non-electrically conductive epoxy.

11. (Currently Amended) The printed circuit board of claim 1, wherein the subsequently-  
applied coating comprises:

a layer of dielectric coating that conformingly coats exposed surfaces of the printed  
wiring board, the component, and the filler material, wherein the openings of ~~the eavity~~ the  
space are sufficiently large to prevent the dielectric coating from bridging across the one or  
more openings ~~of the eavity~~ without the presence of the filler material.

12. (Currently Amended) A printed circuit board comprising:

a printed wiring board;

a plurality of components each having a ~~device~~ component body mounted on said printed wiring board, ~~wherein the printed wiring board has to form one or more printed circuit board regions having a highly variable and cavitations surface including~~ at least one ~~cavity defined~~ volume of space bounded by component leads, the component body adjacent the component leads, and a portion of the printed wiring board below the component leads, wherein each ~~such cavity includes~~ at least one space comprises at least one opening ~~to the~~ on the surface of the printed circuit board; and

a layer of non-electrically-conductive filler material adhered to printed circuit board surfaces ~~in at least one of the one or more regions~~ to provide a contoured, contiguous filler material surface having gradual transitions, wherein the filler material at least partially infills the at least one ~~cavity~~ space through the at least one opening, and further wherein the filler material bridges across the at least one ~~cavity~~ opening so as to encapsulate and seal the ~~cavity~~ at least one space.

13. (Original) The printed circuit board of claim 12, wherein said filler material is thixotropic.

14. (Previously Presented) The printed circuit board of claim 12, wherein said filler material is an epoxy.

15. (Currently Amended) The printed circuit board of claim 14, further comprising:

a low viscosity, high adherence dielectric coating that, when applied and cured, covers ~~predetermined~~ portions of said printed circuit board ~~including at least a portion of the one or more regions~~ coated with said the filler material, wherein the filler material prevents the dielectric coating from entering the at least one ~~cavity~~ opening of the at least one space.

16. (Previously Presented) The printed circuit board of claim 15, further comprising:

a conductive coating covering said dielectric coating and portions of the printed circuit board not covered by the dielectric coating, wherein the dielectric coating and the

conductive coating form a conformal EMI shield that adheres to and conforms with the printed circuit board surfaces.

17. (Original) The printed circuit board of claim 14, wherein said filler material is thixotropic.

18-21 (Canceled)